



NOTES:
 1. THE TERMINAL PITCH MEANS THE DISTANCES BETWEEN THE TERMINAL CENTERS.
 2. PACKAGE OUTLINE DOES NOT INCLUDE MOLD FLASH.

DKI ELECTRIC INDUSTRY Co.,LTD. LSI DIV. PACKAGE ENGINEERING DEPT.					
PACKAGE MATERIAL	EPOXY RESIN	UNIT	mm	SCALE	10/1
BALL MATERIAL	Sn/Pb	DWG No.	QSL-39024		
PACKAGE MASS (g)	0.04TYP.	TITLE	P-VFLGA48-6.26x5.98-0.80-W		
		DESIGNED			/ /
REVISION	1	CHECKED			/ /
REVISED	/ /	CHECKED			/ /
ISSUED	/ /	APPROVED			/ /